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## What is Clamed is:

A semiconductor device for detecting a neutron comprising:
a semiconductor substrate; and
a boron containing layer containing isotope <sup>10</sup>B, the layer being
formed on said semiconductor substrate.

2. A semiconductor device according to claim 1, further comprising a PN junction formed on a surface area of said semiconductor substrate below said boron containing layer; wherein

an electron positive hole pair are generated in a depletion layer of said PN junction by  $\alpha$  ray generated by a reaction between said neutron and said isotope <sup>10</sup> B; and

the neutrons is detected on the basis of the quantity of electric charge of the electron- positive hole pairs.

- 3. A semiconductor device according to claim 2, further comprising an analyzing circuit portion including a predetermined semiconductor element on said semiconductor substrate in a region other than the region where said neutron is detected.
- 4. A semiconductor device according to claim 3, wherein the concentration of said isotope <sup>10</sup> B in said boron containing layer in said analyzing circuit portion is lower than that of said isotope <sup>10</sup> B of said boron containing layer in the region where said neutron is detected.
- 5. A semiconductor device according to claim 3, wherein no boron containing layer is provided on said analyzing circuit portion.
  - 6. A method for fabricating a semiconductor device for detecting

a neutron comprising the steps of :

doping a predetermined impurity into a first region on a semiconductor substrate to form a PN junction on a surface region of said semiconductor substrate;

forming an analyzing circuit section in a second region of said semiconductor substrate for analyzing detected neutron; and

forming a boron containing layer that contains an isotope  $^{10}$  B that reacts with said neutron to generate an  $\alpha$  ray on said semiconductor substrate in at least said first region.

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7. A method for fabricating a semiconductor device according to claim 6, wherein said boron containing layer is formed on said semiconductor substrate in said first and second regions, and

said concentration of said isotope <sup>10</sup> B in said second region is lower than that of said isotope <sup>10</sup> B in the first region.

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8. A method for fabricating a semiconductor device according to claim 6, wherein said boron containing layer is formed only on said semiconductor substrate in said first region.

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